

Erratum to: Active thermal management of on-chip hot spots using EWOD-driven droplet microfluidics

J.-T. Cheng · C.-L. Chen

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J.-T. Cheng (✉) · C.-L. Chen
Teledyne Scientific Company, 1049 Camino Dos Rios,
Thousand Oaks, CA 91360, USA
e-mail: jcheng@teledyne-si.com; jiangtao.cheng@gmail.com